

1 **In the Specification**

2 On page 2, line 7, replace "apparatuses" with --apparatus--.

3 On page 2, line 10, replace "apparatuses" with --apparatus--.

4 On page 8, line 10, following "laser" insert --beam--.

5
6 **In the Claims**

7 1. (Amended) A method of bonding [solder] balls of solder to
8 bond pads on a substrate comprising:

9 contemporaneously retaining at least two [solder] balls of solder
10 over different respective bond pads on a substrate in the absence of
11 flux; and

12 with [said] the balls so retained, exposing the balls to bonding
13 conditions effective to bond the balls with their associated bond pads.

14
15 2. (Amended) The method of claim 1, wherein [the] exposing
16 [of the balls] comprises laser-bonding the balls.